



# SOT1411-1

WLCSP12, wafer level chip scribe package, 12 terminals, 1.58 mm x 2.15 mm x 0.22 mm body

26 November 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP12
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	27-09-2010
<b>Manufacturer package code</b>	SOT1411-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.58	-	mm
package width	-	2.15	-	mm
seated height	-	0.22	-	mm
actual quantity of termination	-	12	-	



2 Package outline

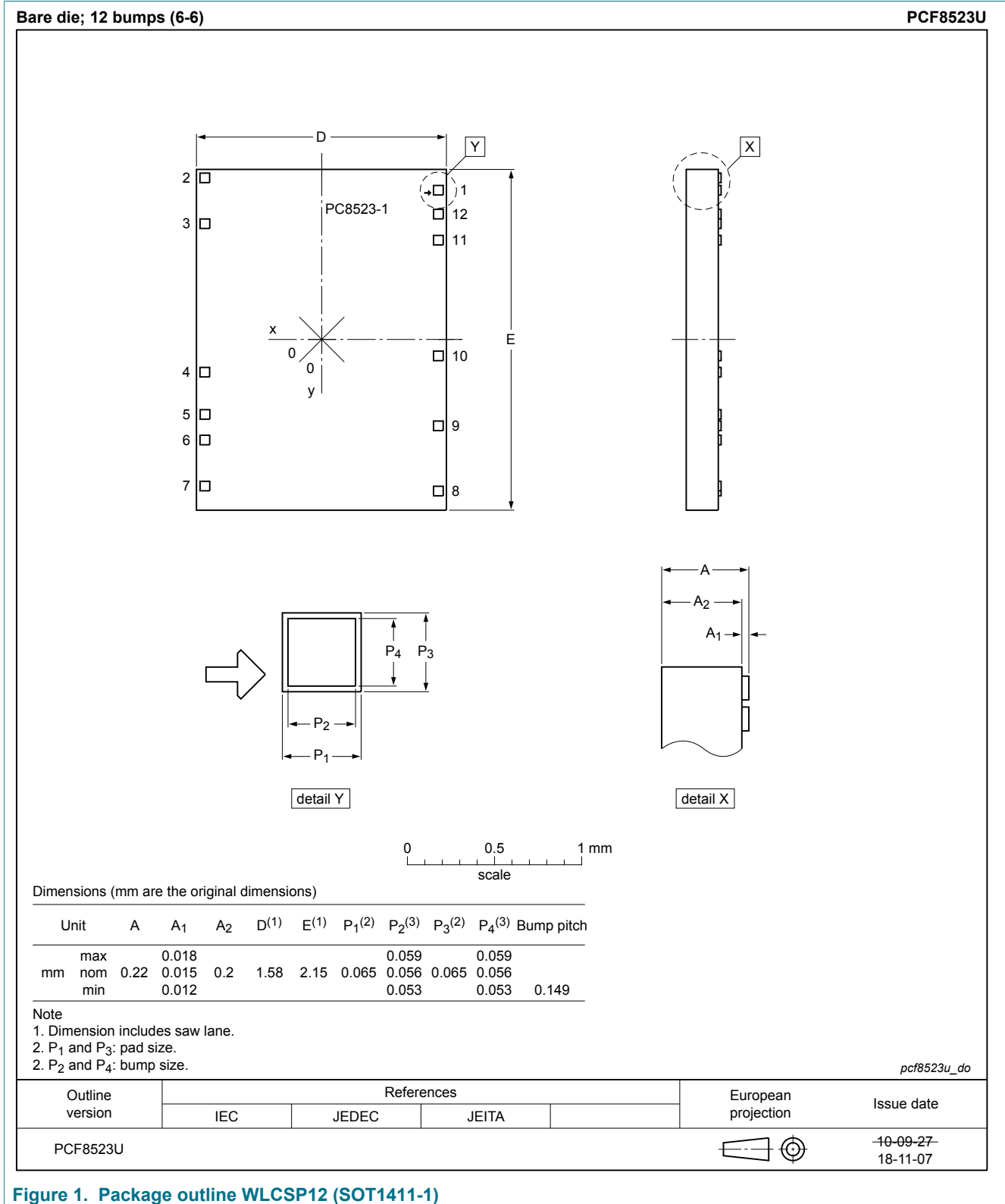


Figure 1. Package outline WLCSP12 (SOT1411-1)

### 3 Legal information

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